

ABSTRACT OF DISCLOSURE

A device and method for enclosing electronics in a waterproof environment and transferring the heat generated by the electronics to an external environment is provided. The device includes a housing and a heat sink. The housing includes top and bottom pieces that are sealed to one another forming an interior portion. The interior portion houses electronic components. A face plate is coupled to the front of the housing and includes an opening that is sealed with a hinged door. A fastening mechanism securely fastens the heat sink to the housing so that a substantial portion of the heat sink is in contact with the back side of housing. Heat sink includes a base and a plurality of fins that are adapted to transfer heat generated by the electronic components within the interior of the housing to an external environment.